FY2025
Financial Results Briefing

February 6, 2026

MEIKO ELECTRONICS CO., LTD.
(Securities Identification Code: 6787)

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Financial Results

(billion yen)

		FY2024		FY2025		Y on Y Change	
		9 months	%	9 months	%	Diff.	%
Net sales	PCB	125.7		142.2		16.5	13.1%
	Electronic Equipment	26.1		29.8		3.7	14.2%
		151.8		172.0		20.2	13.4%
Operating income	PCB	13.2	10.5%	15.4	10.7%	2.2	16.7%
	Electronic Equipment	1.4	5.4%	2.1	7.0%	0.7	50.0%
		14.6	9.6%	17.5	10.2%	2.9	19.5%
Ordinary income		16.0	10.5%	18.9	11.0%	2.9	18.4%
Net income		12.6	8.3%	14.8	8.6%	2.2	17.7%
Average FX rate (JPY/USD)		153.03		149.28			

Net Sales by Product Application

(billion yen)

	FY2024	FY2025	Y on Y Change	
	9 months	9 months	Diff.	%
Automotive	67.7	72.1	4.4	6.5%
Smartphones Tablets	18.8	20.9	2.1	11.2%
Telecommunications	13.8	18.5	4.7	34.1%
Package	0.8	1.6	0.8	100.0%
Module	9.8	12.2	2.4	24.5%
Amusement/Smart Appliances/Industrial Equipment/Other Substrates	14.8	17.1	2.3	15.5%
PCB	125.7	142.4	16.7	13.3%
EMS	14.0	13.5	-0.5	-3.6%
ODM	12.1	16.1	4.0	33.1%
Electronic Equipment	26.1	29.6	3.5	13.4%
Total	151.8	172.0	20.2	13.4%

Net Sales by Product Specification

(billion yen)

	FY2024	FY2025	Y on Y Change	
	9 months	9 months	Diff.	%
4-layer board or lower	31.9	32.4	0.5	1.6%
6-layer board or higher	24.8	26.6	1.8	7.3%
MLB	**56.7**	**59.0**	**2.3**	**4.1%**
8-layer board or lower	38.1	42.0	3.9	10.2%
10-layer board or higher	25.5	35.6	10.1	39.6%
HDI	**63.6**	**77.6**	**14.0**	**22.0%**
Package	**0.8**	**1.6**	**0.8**	**100.0%**
Flexible/High Dissipation /Other Substrates	**4.6**	**4.2**	**-0.4**	**-8.7%**
PCB	**125.7**	**142.4**	**16.7**	**13.3%**
EMS	14.0	13.5	-0.5	-3.6%
ODM	12.1	16.1	4.0	33.1%
Electronic Equipment	**26.1**	**29.6**	**3.5**	**13.4%**
Total	**151.8**	**172.0**	**20.2**	**13.4%**

FY2025 Forecast Rivision

(billion yen)

		FY2025		FY2025			
		previous forecast	%	Revised forecast	%	Diff.	%
Net sales	PCB	182.0		195.0		13.0	7.1%
	Electronic Equipment	41.0		40.0		-1.0	-2.4%
		223.0		235.0		12.0	5.4%
Operating income	PCB	20.5	11.3%	22.0	11.3%	1.5	7.3%
	Electronic Equipment	3.0	7.3%	3.0	7.5%	0.0	0.0%
		23.5	10.5%	25.0	10.6%	1.5	6.4%
Ordinary income		22.0	9.9%	24.5	10.4%	2.5	11.4%
Net income		18.0	8.1%	20.0	8.5%	2.0	11.1%
Average FX rate (JPY/USD)		143		150		7	4.9%
Dividends (JPY)		90		115		25	27.8%

FY2025 Forecast by Product Application

(billion yen)

		FY2025	FY2025		
		previous forecast	Revised forecast	Diff	%
	Automotive	91.0	96.0	5.0	5.5%
	Smartphones Tablets	28.0	29.5	1.5	5.4%
	Telecommunications	25.0	29.5	4.5	18.0%
	Package	1.5	2.0	0.5	33.3%
	Module	14.0	16.0	2.0	14.3%
	Amusement/Smart Appliances /Industrial Equipment /Other Substrates	22.5	22.0	-0.5	-2.2%
PCB		**182.0**	**195.0**	**13.0**	**7.1%**
	EMS	21.0	18.2	-2.8	-13.3%
	ODM	20.0	21.8	1.8	9.0%
Electronic Equipment		**41.0**	**40.0**	**-1.0**	**-2.4%**
Total		**223.0**	**235.0**	**12.0**	**5.4%**

FY2025 Forecast by Product Specification

(billion yen)

	FY2025	FY2025		
	previous forecast	Revised forecast	Diff	%
4-layer board or lower	39.0	43.5	4.5	11.5%
6-layer board or higher	34.0	35.0	1.0	2.9%
MLB	**73.0**	**78.5**	**5.5**	**7.5%**
8-layer board or lower	56.5	61.0	4.5	8.0%
10-layer board or higher	45.5	48.5	3.0	6.6%
HDI	**102.0**	**109.5**	**7.5**	**7.4%**
Package	**1.5**	**2.0**	**0.5**	**33.3%**
Flexible/High Dissipation /Other Substrates	**5.5**	**5.0**	**-0.5**	**-9.1%**
PCB	**182.0**	**195.0**	**13.0**	**7.1%**
EMS	21.0	18.2	-2.8	-13.3%
ODM	20.0	21.8	1.8	9.0%
Electronic Equipment	**41.0**	**40.0**	**-1.0**	**-2.4%**
Total	**223.0**	**235.0**	**12.0**	**5.4%**